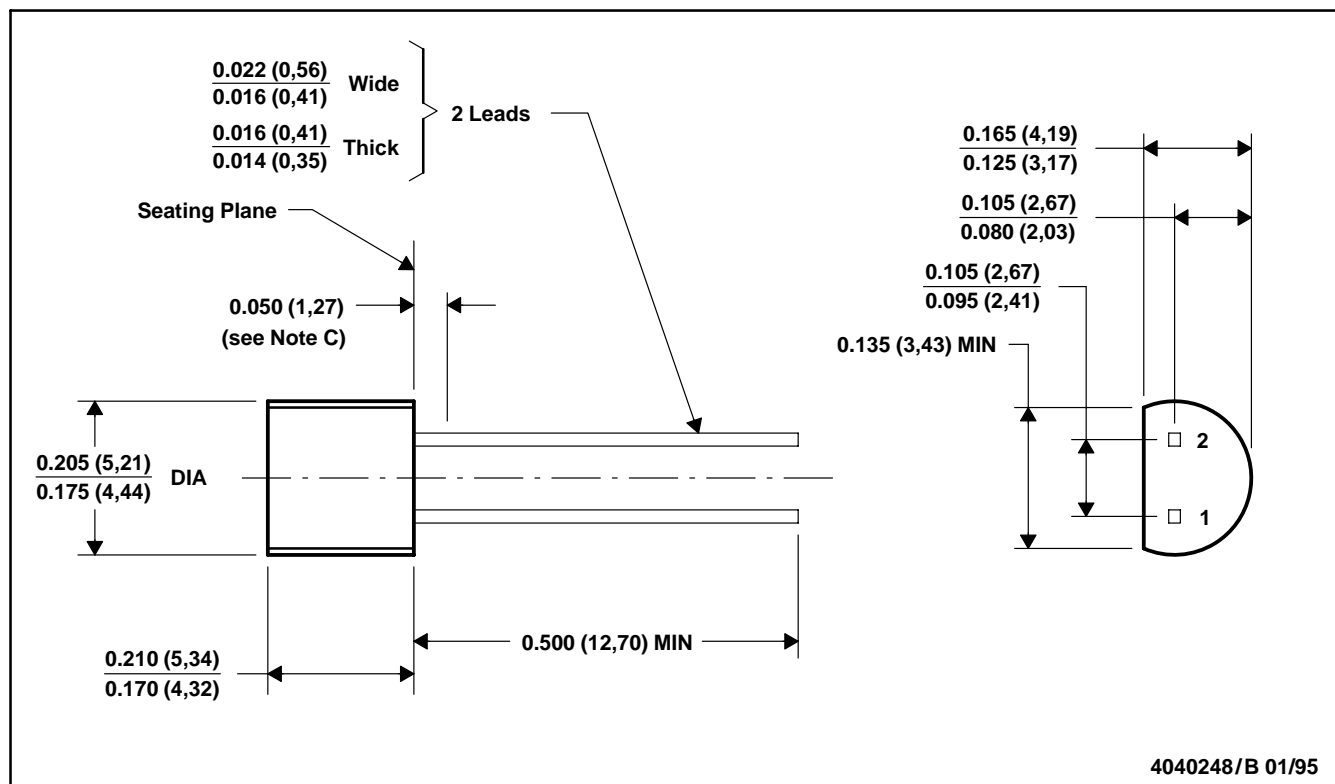


LP (O-PBCY-W2)

PLASTIC CYLINDRICAL PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Lead dimensions are not controlled within this area.
 - Falls within JEDEC TO-226AC (TO-226AC replaces TO-92)

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